



The Future of Analog IC Technology®

# MP9943

## High Efficiency 3A Peak, 36V, Synchronous Step Down Converter With Power Good

### DESCRIPTION

The MP9943 is a high-frequency, synchronous, rectified, step-down, switch-mode converter with built-in power MOSFETs. It offers a very compact solution to achieve a 3A peak output current with excellent load and line regulation over a wide input supply range. The MP9943 has synchronous mode operation for higher efficiency over the output current load range.

Current-mode operation provides fast transient response and eases loop stabilization.

Full protection features include over-current protection and thermal shutdown.

The MP9943 requires a minimal number of readily-available standard external components, and is available in a space-saving QFN-8 (3mmx3mm) package.

### FEATURES

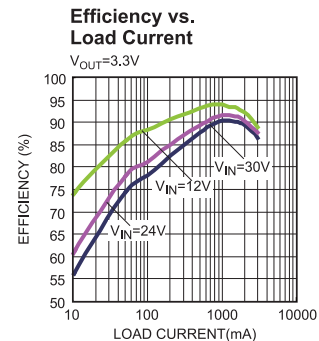
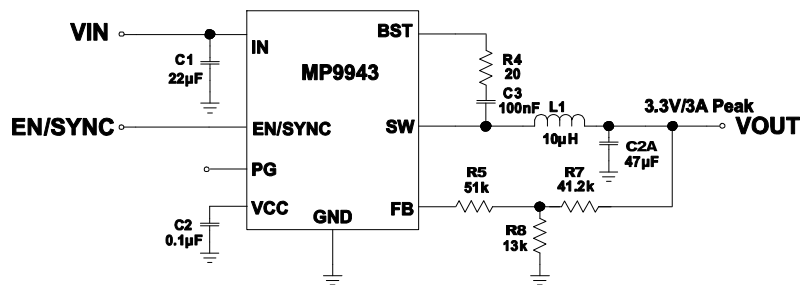
- Wide 4V to 36V Continuous Operating Input Range
- 85mΩ/55mΩ Low  $R_{DS(ON)}$  Internal Power MOSFETs
- High-Efficiency Synchronous Mode Operation
- 410kHz Switching Frequency
- Synchronizes from 200kHz to 2.2MHz External Clock
- High Duty Cycle for Automotive Cold-crank
- Internal Power-Save Mode
- Internal Soft-Start
- Power Good Indicator
- Over Current Protection and Hiccup
- Thermal Shutdown
- Output Adjustable from 0.8V
- Available in an QFN-8 (3mmx3mm) package

### APPLICATIONS

- General Consumer
- Multi-Function Printers (MFP)
- Distributed Power Systems

All MPS parts are lead-free and adhere to the RoHS directive. For MPS green status, please visit MPS website under Quality Assurance. "MPS" and "The Future of Analog IC Technology" are Registered Trademarks of Monolithic Power Systems, Inc.

### TYPICAL APPLICATION



### ORDERING INFORMATION

Part Number*	Package	Top Marking
MP9943GQ	QFN-8 (3mmx3mm)	See Below

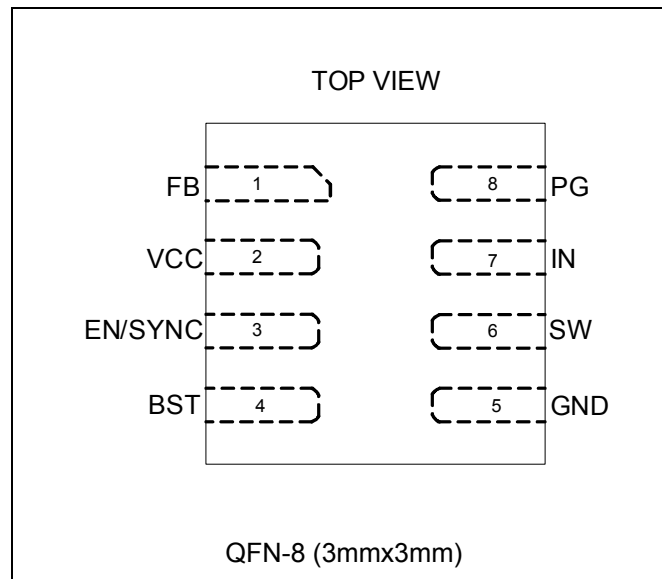
\* For Tape & Reel, add suffix -Z (e.g. MP9943GQ-Z);

### TOP MARKING

\_\_\_\_\_  
**AMGY**  
**LLL**

AMG: product code of MP9943GQ;  
 Y: year code;  
 LLL: lot number;

### PACKAGE REFERENCE



**ABSOLUTE MAXIMUM RATINGS <sup>(1)</sup>**

$V_{IN}$ .....	-0.3V to 40V
$V_{SW}$ .....	-0.3V to 41V
$V_{BS}$ .....	$V_{SW}+6V$
All Other Pins .....	-0.3V to 6V <sup>(2)</sup>
Continuous Power Dissipation ( $T_A = +25^\circ C$ ) <sup>(3)</sup>	
QFN-8 (3mmx3mm) .....	2.27W
Junction Temperature .....	150°C
Lead Temperature .....	260°C
Storage Temperature .....	-65°C to 150°C

**Recommended Operating Conditions <sup>(4)</sup>**

Continuous Supply Voltage $V_{IN}$ .....	4V to 36V
Output Voltage $V_{OUT}$ .....	0.8V to $D_{Max} \times V_{IN}$
Operating Junction Temp ( $T_J$ ) ..	-40°C to +125°C

<b>Thermal Resistance <sup>(5)</sup></b>	<b><math>\theta_{JA}</math></b>	<b><math>\theta_{JC}</math></b>	
QFN-8 (3mmx3mm) .....	55 .....	13...	°C/W

**Notes:**

- 1) Absolute maximum ratings are rated under room temperature unless otherwise noted. Exceeding these ratings may damage the device.
- 2) About the details of EN/SYNC pin's ABS MAX rating, please refer to page 12, Enable/SYNC control section.
- 3) The maximum allowable power dissipation is a function of the maximum junction temperature  $T_J$  (MAX), the junction-to-ambient thermal resistance  $\theta_{JA}$ , and the ambient temperature  $T_A$ . The maximum allowable continuous power dissipation at any ambient temperature is calculated by  $P_D$  (MAX) =  $(T_J$  (MAX)- $T_A$ )/ $\theta_{JA}$ . Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- 4) The device is not guaranteed to function outside of its operation condition.
- 5) Measured on JESD51-7, 4-layer PCB.

## ELECTRICAL CHARACTERISTICS

$V_{IN} = 12V$ ,  $T_J = +25^{\circ}C$ , unless otherwise noted.

Parameter	Symbol	Condition	Min	Typ	Max	Units
Supply Current (Shutdown)	$I_{SHDN}$	$V_{EN} = 0V$			8	$\mu A$
Supply Current (Quiescent)	$I_Q$	$V_{EN} = 2V$ , $V_{FB} = 1V$		0.5	0.7	mA
HS Switch-ON Resistance	$R_{ON\_HS}$	$V_{BST-SW}=5V$		85	105	m $\Omega$
LS Switch-ON Resistance	$R_{ON\_LS}$	$V_{CC} = 5V$		55	75	m $\Omega$
Switch Leakage	$I_{LKG\_SW}$	$V_{EN} = 0V$ , $V_{SW} = 12V$			1	$\mu A$
Current Limit	$I_{LIMIT}$	Under 40% Duty Cycle	3.2	4.4	5.5	A
Oscillator Frequency	$f_{SW}$	$V_{FB}=750mV$	320	410	500	kHz
Fold-Back Frequency	$f_{FB}$	$V_{FB}<400mV$	70	100	130	kHz
Maximum Duty Cycle	$D_{MAX}$	$V_{FB}=750mV$ , 410kHz	92	95		%
Minimum ON Time <sup>(6)</sup>	$t_{ON\_MIN}$			70		ns
Sync Frequency Range	$f_{SYNC}$		0.2		2.4	MHz
Feedback Voltage	$V_{FB}$		778	792	806	mV
Feedback Current	$I_{FB}$	$V_{FB}=820mV$		10	100	nA
EN Rising Threshold	$V_{EN\_RISING}$		1.15	1.4	1.65	V
EN Falling Threshold	$V_{EN\_FALLING}$		1.05	1.25	1.45	V
EN Threshold Hysteresis	$V_{EN\_HYS}$			150		mV
EN Input Current	$I_{EN}$	$V_{EN}=2V$		4	6	$\mu A$
		$V_{EN}=0$		0	0.2	$\mu A$
VIN Under-Voltage Lockout Threshold-Rising	$INUV_{RISING}$		3.3	3.5	3.7	V
VIN Under-Voltage Lockout Threshold-Falling	$INUV_{FALLING}$		3.1	3.3	3.5	V
VIN Under-Voltage Lockout Threshold-Hysteresis	$INUV_{HYS}$			200		mV
VCC Regulator	$V_{CC}$	$I_{CC}=0mA$	4.6	4.9	5.2	V
VCC Load Regulation		$I_{CC}=5mA$		1.5	4	%
Soft-Start Period	$t_{SS}$	$V_{OUT}$ from 10% to 90%	0.45	1.5	2.55	ms
Thermal Shutdown <sup>(6)</sup>	$T_{SD}$		150	170		$^{\circ}C$
Thermal Hysteresis <sup>(6)</sup>	$T_{SD\_HYS}$			30		$^{\circ}C$
PG Rising Threshold	$PG_{Vth\_RISING}$	as percentage of $V_{FB}$	86	90	94	%
PG Falling Threshold	$PG_{Vth\_FALLING}$	as percentage of $V_{FB}$	80	84	88	%

**ELECTRICAL CHARACTERISTICS (continued)**
 **$V_{IN} = 12V$ ,  $T_J = +25^{\circ}C$ , unless otherwise noted.**

Parameter	Symbol	Condition	Min	Typ	Max	Units
PG Threshold Hysteresis	$PG_{Vth\_HYS}$	as percentage of $V_{FB}$		6		%
PG Rising Delay	$PG_{Td\_RISING}$		40	90	160	$\mu s$
PG Falling Delay	$PG_{Td\_FALLING}$		30	55	95	$\mu s$
PG Sink Current Capability	$V_{PG}$	Sink 4mA		0.1	0.3	V
PG Leakage Current	$I_{LKG\_PG}$			10	100	nA

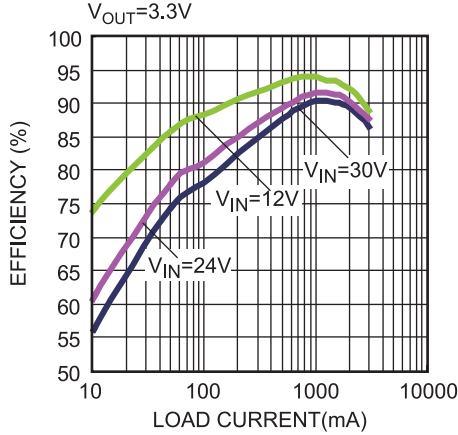
**Notes:**

6) Derived from bench characterization. Not tested in production.

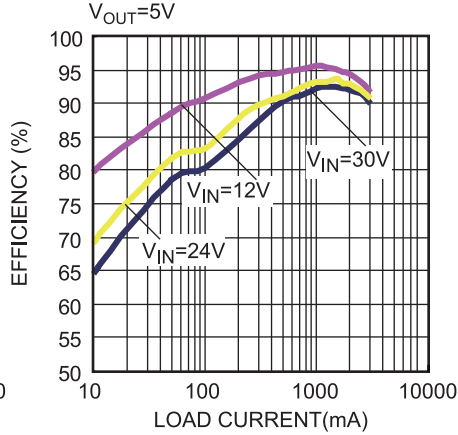
**TYPICAL PERFORMANCE CHARACTERISTICS**

$V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 10\mu H$ ,  $R_{BST}=20\Omega$ ,  $T_A = +25^\circ C$ , unless otherwise noted.

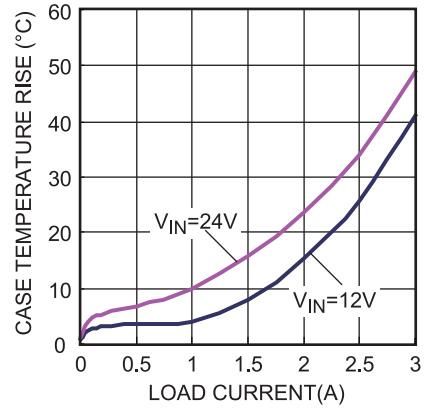
**Efficiency vs. Load Current**



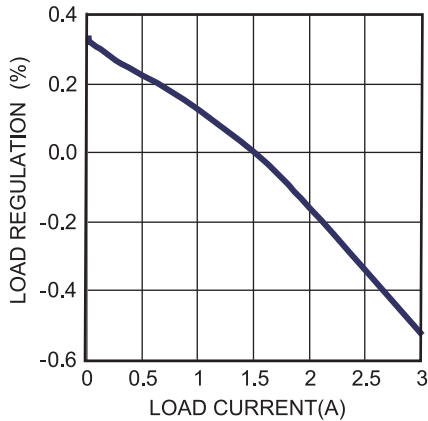
**Efficiency vs. Load Current**



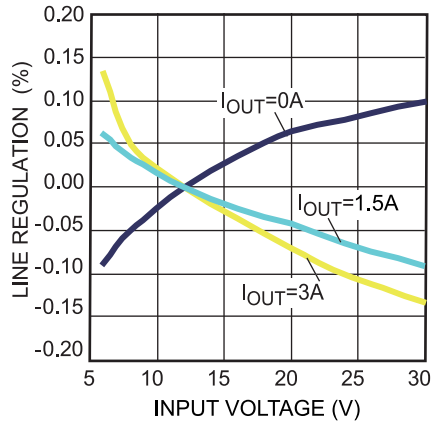
**Thermal Rise**

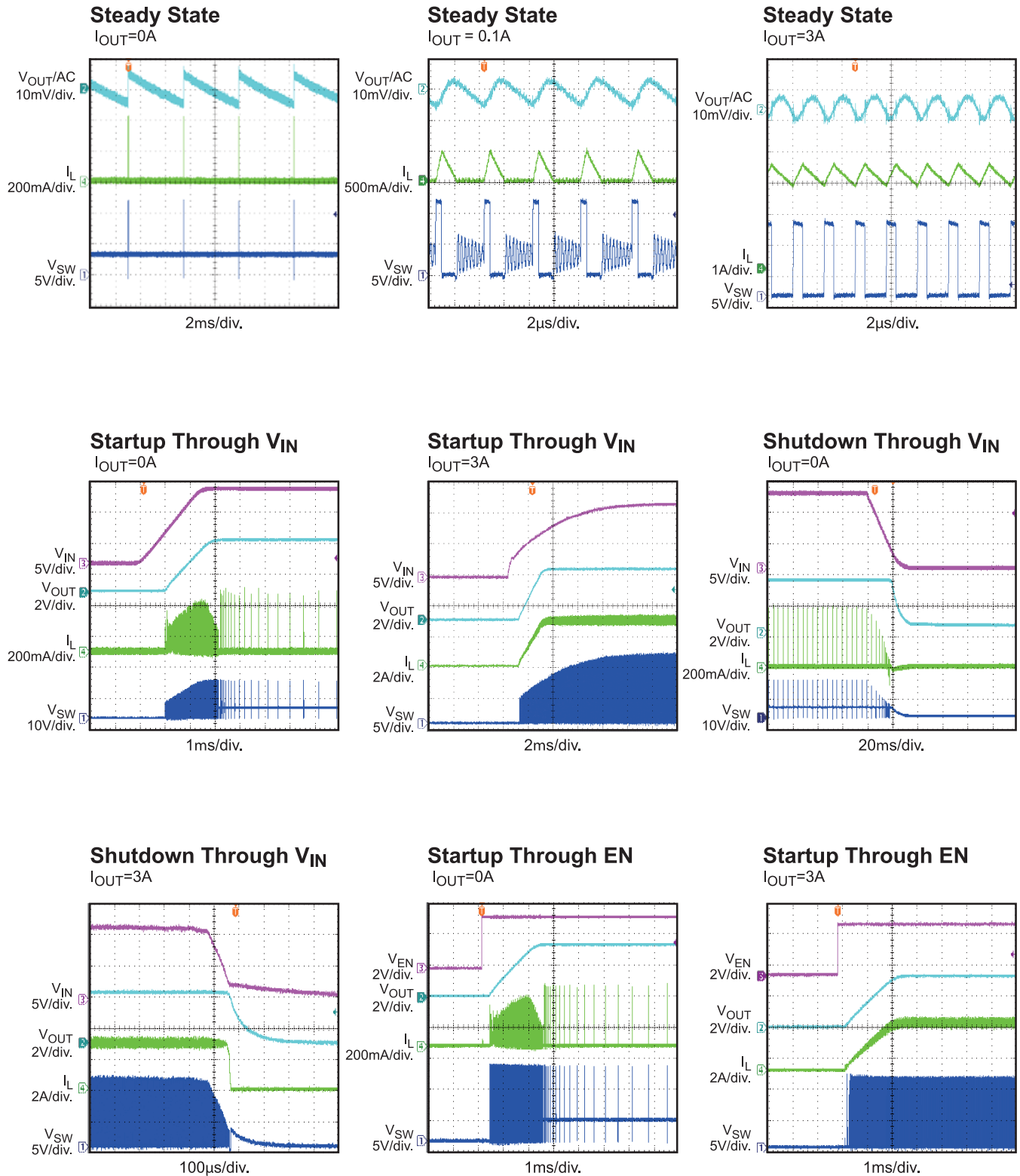


**Load Regulation**



**Line Regulation**



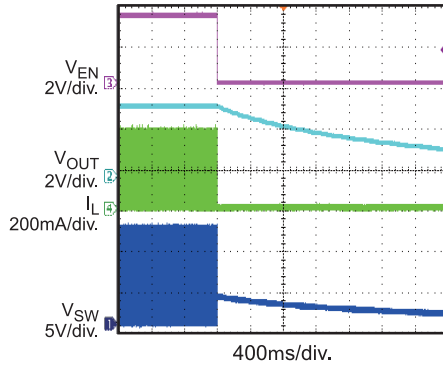
**TYPICAL PERFORMANCE CHARACTERISTICS**
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**TYPICAL PERFORMANCE CHARACTERISTICS**

$V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 10\mu H$ ,  $R_{BST}=20\Omega$ ,  $T_A = +25^\circ C$ , unless otherwise noted.

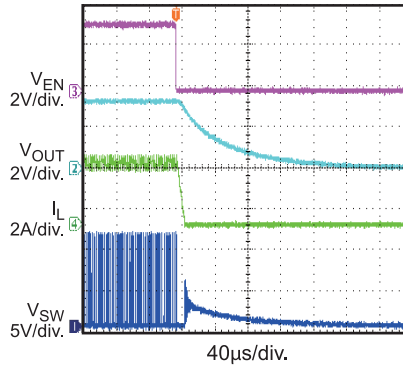
**Shutdown Through EN**

$I_{OUT}=0A$



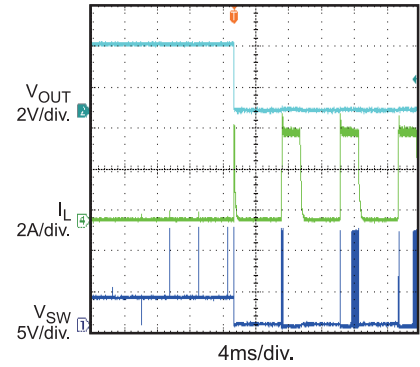
**Shutdown Through EN**

$I_{OUT}=3A$



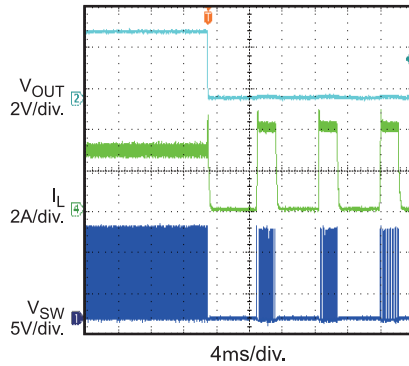
**SCP Entry**

$I_{OUT}=0A$  to Short Circuit

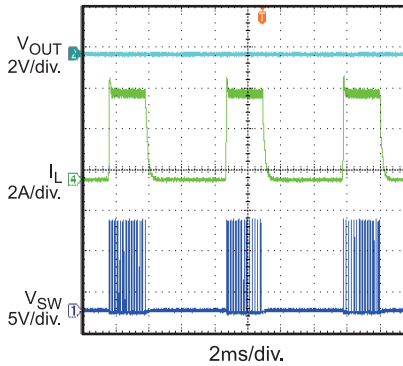


**SCP Entry**

$I_{OUT}=3A$  to Short Circuit

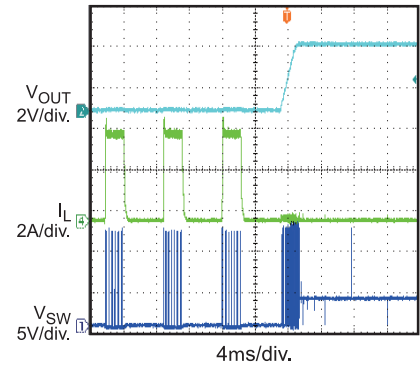


**SCP Steady State**



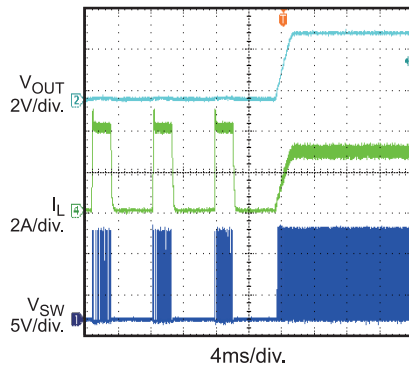
**SCP Recovery**

Short Circuit to  $I_{OUT}=0A$



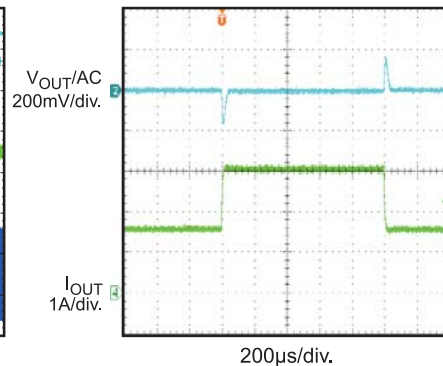
**SCP Recovery**

Short Circuit to  $I_{OUT}=3A$



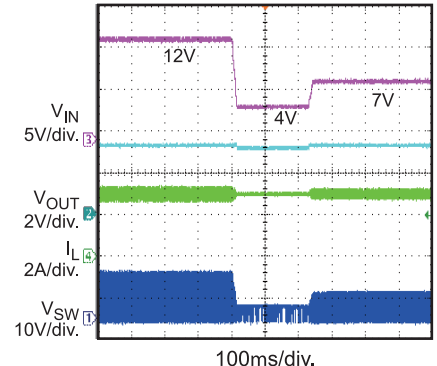
**Load Transient**

$I_{OUT}=1.5A \leftrightarrow 3A$ ,  $1.6A/\mu s$



**Cold-Crank**

$V_{OUT}=3.3V$ ,  $I_{OUT}=3A$



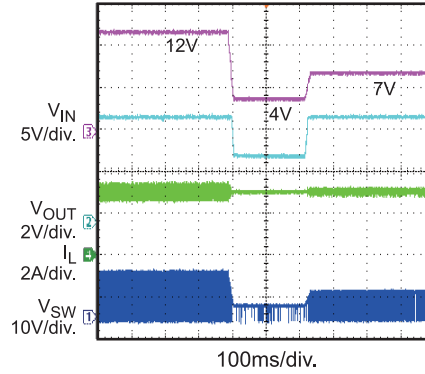


**TYPICAL PERFORMANCE CHARACTERISTICS**

$V_{IN} = 12V$ ,  $V_{OUT} = 3.3V$ ,  $L = 10\mu H$ ,  $R_{BST}=20\Omega$ ,  $T_A = +25^\circ C$ , unless otherwise noted.

**Cold-Crank**

$V_{OUT}=5V$ ,  $I_{OUT}=3A$



## PIN FUNCTIONS

Package Pin #	Name	Description
1	FB	Feedback. Connect to the tap of an external resistor divider from the output to GND, to set the output voltage. The frequency fold-back comparator lowers the oscillator frequency when the FB voltage is below 660mV to prevent current limit runaway during a short-circuit fault condition.
2	VCC	Bias Supply. Decouple with 0.1 $\mu$ F-to-0.22 $\mu$ F capacitor. Select a capacitor that does not exceed 0.22 $\mu$ F
3	EN/SYNC	Enable/Synchronize. EN/SYNC high to enable the MP9943. Apply an external clock to the EN/SYNC pin to change the switching frequency.
4	BST	Bootstrap. Requires a capacitor connected between SW and BST pins to form a floating supply across the high-side switch driver. A 20 $\Omega$ resistor placed between SW and BST cap is strongly recommended to reduce SW spike voltage.
5	GND	System Ground. This pin is the reference ground of the regulated output voltage, and PCB layout requires special care. For best results, connect to GND with copper traces and vias.
6	SW	Switch Output. Connect with a wide PCB trace.
7	IN	Supply Voltage Input. The MP9943 operates from a 4V to 36V input rail. Requires C1 to decouple the input rail. Connect using a wide PCB trace.
8	PG	Power Good. The output of this pin is an open drain and goes high if the output voltage exceeds 90% of the nominal voltage.

### FUNCTIONAL BLOCK DIAGRAM

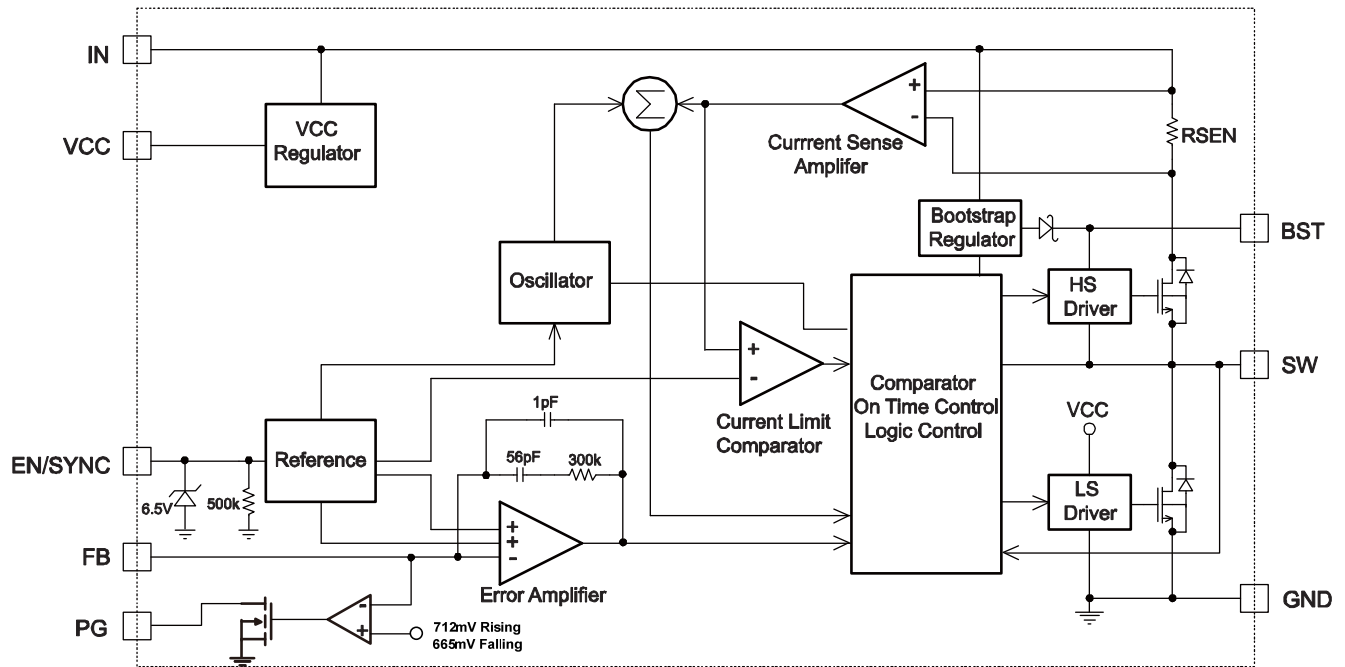


Figure 1: Functional Block Diagram



### Under-Voltage Lockout

Under-voltage lockout (UVLO) protects the chip from operating at an insufficient supply voltage. The MP9943 UVLO comparator monitors the output voltage of the internal regulator, VCC. The UVLO rising threshold is about 3.5V while its falling threshold is 3.3V.

### Internal Soft-Start

The soft-start prevents the converter output voltage from overshooting during startup. When the chip starts, the internal circuitry generates a soft-start voltage (SS) that ramps up from 0V to 1.2V. When SS is lower than REF, SS overrides REF so the error amplifier uses SS as the reference. When SS exceeds REF, the error amplifier uses REF as the reference. The SS time is internally set to 1.5ms.

### Over-Current Protection and Hiccup

The MP9943 has cycle-by-cycle over current limit when the inductor current peak value exceeds the set current limit threshold. If the output voltage starts to drop until FB is below the Under-Voltage (UV) threshold—typically 84% below the reference—the MP9943 enters hiccup mode to periodically restart the part. This protection mode is especially useful when the output is dead-shortened to ground. The average short-circuit current is greatly reduced to alleviate the thermal issue and to protect the regulator. The MP9943 exits the hiccup mode once the over-current condition is removed.

### Thermal Shutdown

Thermal shutdown prevents the chip from operating at exceedingly high temperatures. When the silicon die temperature exceeds 170°C, it shuts down the whole chip. When the temperature drops below its lower threshold (typically 140°C) the chip is enabled again.

### Floating Driver and Bootstrap Charging

An external bootstrap capacitor power the floating-power-MOSFET driver. A dedicated internal regulator (see Figure 4) charges and regulates the bootstrap capacitor voltage to ~5V. When the voltage between the BST and SW nodes drops below regulation, a PMOS pass transistor connected from V<sub>IN</sub> to BST turns on. The charging current path is from V<sub>IN</sub>, BST and then to SW. The external circuit should provide

enough voltage headroom to facilitate charging. As long as V<sub>IN</sub> is significantly higher than SW, the bootstrap capacitor remains charged. When the HS-FET is on, V<sub>IN</sub> ≈ V<sub>SW</sub>, so the bootstrap capacitor can't be charged. When the LS-FET is on, V<sub>IN</sub>-V<sub>SW</sub> reaches its maximum for fast charging. When there is no inductor current, V<sub>SW</sub>=V<sub>OUT</sub>, so the difference between V<sub>IN</sub> and V<sub>OUT</sub> can charge the bootstrap capacitor. The floating driver has its own UVLO protection, with a rising threshold of 2.2V and hysteresis of 150mV. A 20Ω resistor placed between SW and BST cap is strongly recommended to reduce SW spike voltage.

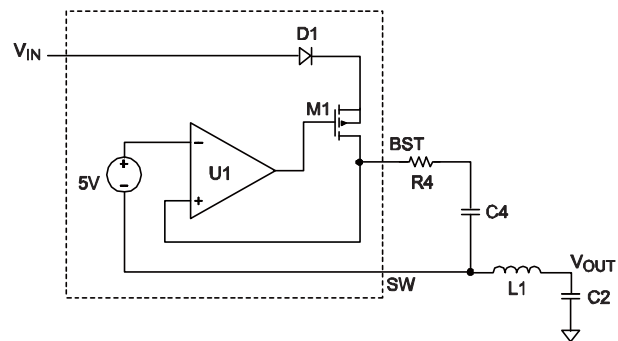


Figure 4: Internal Bootstrap Charging Circuit

### Startup and Shutdown

If both V<sub>IN</sub> and V<sub>EN/SYNC</sub> exceed their appropriate thresholds, the chip starts: The reference block starts first, generating stable reference voltage and currents, and then the internal regulator is enabled. The regulator provides stable supply for the remaining circuitries.

Three events can shut down the chip: V<sub>EN/SYNC</sub> low, V<sub>IN</sub> low, and thermal shutdown. In the shutdown procedure, the signaling path is first blocked to avoid any fault triggering. The COMP voltage and the internal supply rail are then pulled down. The floating driver is not subject to this shutdown command.

### Power Good

The MP9943 has power good (PG) output. The PG pin is the open drain of a MOSFET. It should be connected to VCC or some other voltage source through a resistor (e.g. 100kΩ). In the presence of an input voltage, the MOSFET turns on so that the PG pin is pulled to low before SS

is ready. After  $V_{FB}$  reaches  $90\% \times REF$ , the PG pin is pulled high after a delay, typically  $90\mu s$ . When  $V_{FB}$  drops to  $84\% \times REF$ , the PG pin is pulled low. Also, PG is pulled low if thermal shutdown or EN/SYNC is pulled low.

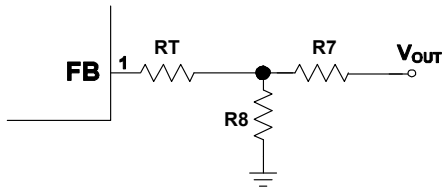
## APPLICATION INFORMATION

### Setting the Output Voltage

The external resistor divider sets the output voltage (see Typical Application on page 1). Choose R7 around 41.2kΩ. R8 is then given by:

$$R8 = \frac{R7}{\frac{V_{OUT}}{0.792V} - 1}$$

The T-type network—as shown in Figure —is highly recommended when V<sub>OUT</sub> is low.



**Figure 5: T-Type Network**

RT+R7 is used to set the loop bandwidth. Basically, higher RT+R7, lower bandwidth. To ensure the loop stability, it is strongly recommended to limit the bandwidth lower than 40kHz based on the 410kHz default fsw. Table 1 lists the recommended T-type resistors value for common output voltages.

**Table 1: Resistor Selection for Common Output Voltages<sup>(7)</sup>**

V <sub>OUT</sub> (V)	R7 (kΩ)	R8 (kΩ)	RT (kΩ)
3.3	41.2 (1%)	13 (1%)	51 (1%)
5	41.2 (1%)	7.68 (1%)	51 (1%)

**Notes:**

7) The recommended parameters is basing on 410kHz switching frequency, different input voltage, output inductor value and output capacitor value may affect the select of R7, R8 and RT. For other components' parameters, please refer to TYPICAL APPLICATION CIRCUITS on page 19.

### Selecting the Inductor

Use a 1μH-to-10μH inductor with a DC current rating of at least 25% percent higher than the maximum load current for most applications. For highest efficiency, an inductor with small DC resistance is recommended. For most designs, the inductance value can be derived from the following equation.

$$L_1 = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times \Delta I_L \times f_{OSC}}$$

Where ΔI<sub>L</sub> is the inductor ripple current.

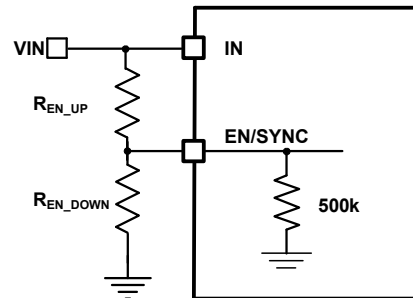
Choose the inductor ripple current to be approximately 30% of the maximum load current. The maximum inductor peak current is:

$$I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_L}{2}$$

Use a larger inductor for improved efficiency under light-load conditions—below 100mA.

### VIN UVLO Setting

MP9943 has internal fix under voltage lock out (UVLO) threshold: rising threshold is 3.5V while falling threshold is about 3.3V. For the application needs higher UVLO point, external resistor divider between EN/SYNC and IN as shown in Figure 6 can be used to get higher equivalent UVLO threshold.



**Figure 6: Adjustable UVLO using EN/SYNC divider**

The UVLO threshold can be computed from below two equations:

$$INUV_{RISING} = \left(1 + \frac{R_{EN\_UP}}{500k/R_{EN\_DOWN}}\right) \times V_{EN\_RISING}$$

$$INUV_{FALLING} = \left(1 + \frac{R_{EN\_UP}}{500k/R_{EN\_DOWN}}\right) \times V_{EN\_FALLING}$$

Where V<sub>EN\_RISING</sub>=1.4V, V<sub>EN\_FALLING</sub>=1.25V.

When choose R<sub>EN\_UP</sub>, make sure it is big enough to limit the current flows into EN/SYNC pin lower than 150μA.

### Selecting the Input Capacitor

The input current to the step-down converter is discontinuous, therefore requires a capacitor is to supply the AC current to the step-down converter while maintaining the DC input voltage. Use low ESR capacitors for the best performance. Use ceramic capacitors with X5R or X7R dielectrics for best results because of their low ESR and small temperature coefficients.

For most application, a 22µF ceramic capacitor is sufficient to maintain the DC input voltage. And it is strongly recommended to use another lower value capacitor (e.g. 1µF) with small package size (0603) to absorb high frequency switching noise. Make sure place the small size capacitor as close to IN and GND pins as possible (see PCB LAYOUT section).

Since C1 absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in the input capacitor can be estimated by:

$$I_{C1} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)}$$

The worse case condition occurs at  $V_{IN} = 2V_{OUT}$ , where:

$$I_{C1} = \frac{I_{LOAD}}{2}$$

For simplification, choose an input capacitor with an RMS current rating greater than half of the maximum load current.

The input capacitor can be electrolytic, tantalum or ceramic. When using electrolytic or tantalum capacitors, add a small, high quality ceramic capacitor (e.g. 1µF) placed as close to the IC as possible. When using ceramic capacitors, make sure that they have enough capacitance to provide sufficient charge to prevent excessive voltage ripple at input. The input voltage ripple caused by capacitance can be estimated by:

$$\Delta V_{IN} = \frac{I_{LOAD}}{f_s \times C1} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$

### Selecting the Output Capacitor

The output capacitor (C2) maintains the DC output voltage. Use ceramic, tantalum, or low-

ESR electrolytic capacitors. For best results, use low ESR capacitors to keep the output voltage ripple low. The output voltage ripple can be estimated by:

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_s \times L_1} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \times \left(R_{ESR} + \frac{1}{8 \times f_s \times C2}\right)$$

Where  $L_1$  is the inductor value and  $R_{ESR}$  is the equivalent series resistance (ESR) value of the output capacitor.

For ceramic capacitors, the capacitance dominates the impedance at the switching frequency, and the capacitance causes the majority of the output voltage ripple. For simplification, the output voltage ripple can be estimated by:

$$\Delta V_{OUT} = \frac{V_{OUT}}{8 \times f_s^2 \times L_1 \times C2} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right)$$

For tantalum or electrolytic capacitors, the ESR dominates the impedance at the switching frequency. For simplification, the output ripple can be approximated to:

$$\Delta V_{OUT} = \frac{V_{OUT}}{f_s \times L_1} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \times R_{ESR}$$

The characteristics of the output capacitor also affect the stability of the regulation system. The MP9943 can be optimized for a wide range of capacitance and ESR values.

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### BST Resistor and External BST Diode

A 20Ω resistor in series with BST capacitor is recommended to reduce the SW spike voltage. Higher resistance is better for SW spike reduction, but will compromise the efficiency on the other hand.

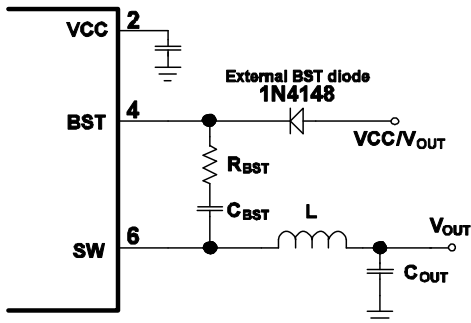
BST voltage may become insufficient at some particular specs. In this case an external bootstrap diode can enhance the efficiency of the regulator and avoid BST voltage insufficient at light load PFM operation. The BST voltage insufficient is more likely to happen at given either of following conditions:



- $V_{IN}$  is below 5V
- $V_{OUT}$  is 5V or 3.3V; and  $D_{uty}$  cycle is high:  

$$D = \frac{V_{OUT}}{V_{IN}} > 65\%$$

In these cases, if BST voltage insufficient happens, the output ripple voltage may become extremely large at light load condition, add an external BST diode from the VCC pin or  $V_{OUT}$  to BST pin, as shown in Figure 7.



**Figure 7: Optional External Bootstrap Diode to Enhance Efficiency**

The recommended external BST diode is 1N4148, and the BST capacitor value is 0.1 $\mu$ F to 1 $\mu$ F.

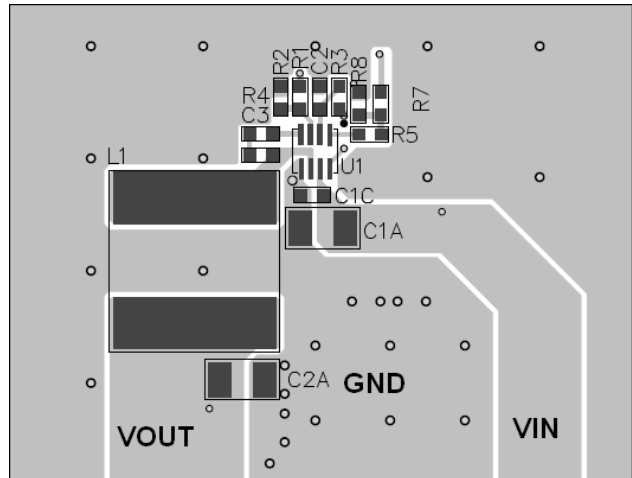
**PCB Layout<sup>(8)</sup>**

PCB layout, especially the input capacitor and VCC capacitor placement, is very important to achieve stable operation. For the best results, follow these guidelines:

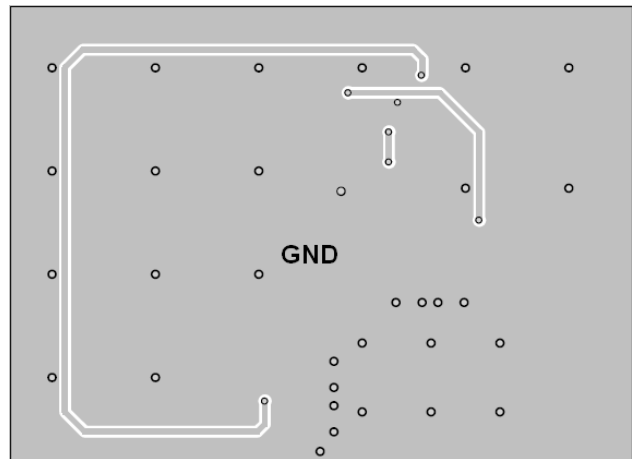
- 1) Place the ceramics input capacitor as close to IN and GND pins as possible, especially the small package size (0603) input bypass capacitor. Keep the connection of input capacitor and IN pin as short and wide as possible.
- 2) Place the VCC capacitor to VCC pin and GND pin as close as possible. Make the trace length of VCC pin-VCC capacitor anode-VCC capacitor cathode-chip GND pin as short as possible.
- 3) Use large ground plane directly connect to GND pin. Add vias near the GND pin if bottom layer is ground plane.
- 4) Route SW, BST away from sensitive analog areas such as FB.
- 5) Place the T-type feedback resistor close to chip to ensure the trace which connects to FB pin as the short as possible.

**Notes:**

- 8) The recommended layout is based on the Figure 9 Typical Application circuit on page 19.



Top Layer



Bottom Layer

**Figure 8: Recommended PCB Layout**

**Design Example**

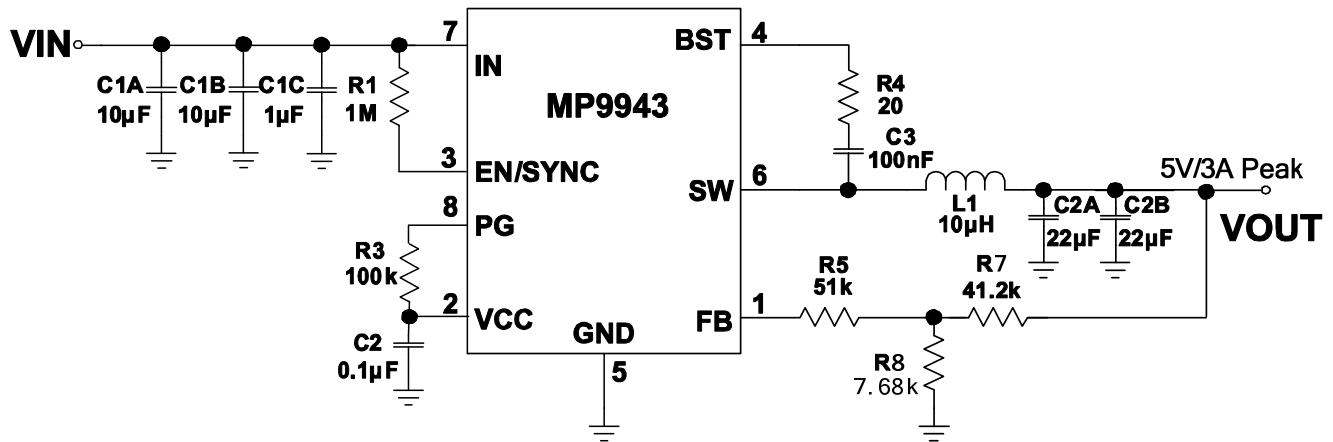
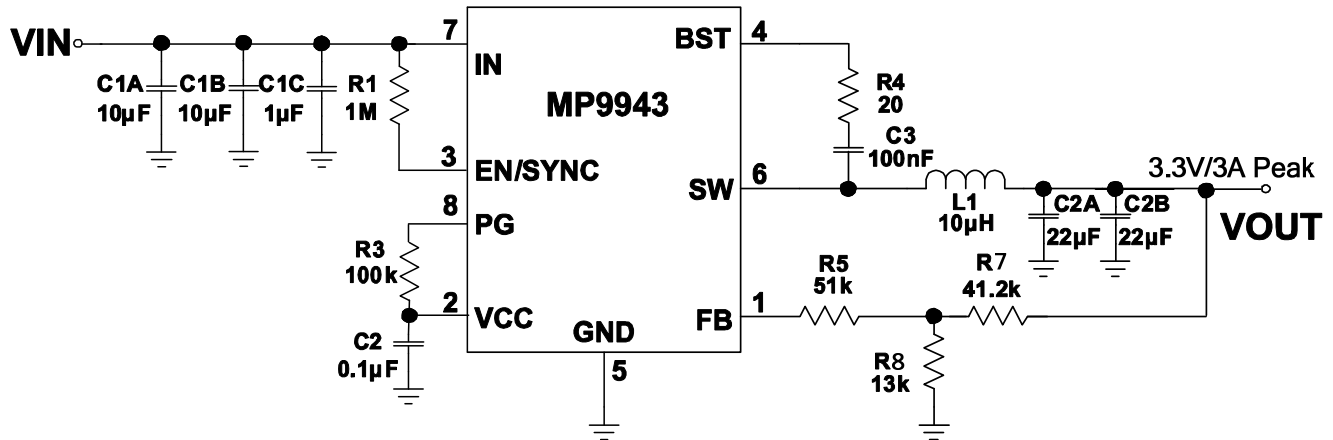
Below is a design example following the application guidelines for the specifications:

**Table 2: Design Example**

<b>V<sub>IN</sub></b>	12V
<b>V<sub>OUT</sub></b>	5V
<b>I<sub>OUT</sub></b>	3A Peak

The detailed application schematic is shown in Figure 9. The typical performance and circuit waveforms have been shown in the Typical Performance Characteristics section. For more device applications, please refer to the related Evaluation Board Datasheets.

## TYPICAL APPLICATION CIRCUITS


 Figure 9: 12V<sub>IN</sub>, 5V/3A Peak Output

 Figure 10: 12V<sub>IN</sub>, 3.3V/3A Peak Output